Amendments To The Claims:

This listing of claims will replace all prior claim lists in this application.

Listing of Claims:

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This listing of claims will replace all prior version and listings of claims in the application:

Listing of Claims:

1. (Currently amended) A method of processing a workpiece, the method comprising the steps of:

fastening a workpiece to be processed to a work carrier by means of a solid that is applied in liquefied form,

wherein the work carrier comprises a porous material including a plurality of pores at least a portion of which are interconnected, and

wherein the plurality of pores are configured to accommodate a portion of the liquefied solid upon application of vacuum pressure to the work carrier.

2. (Previously presented) The method as claimed in claim 1, wherein the work carrier comprises a gas-permeable work carrier.

3. (Currently amended) The method as claimed in claim 1 ~~or 2~~, wherein the solid functions to separate the workpiece and the work carrier, wherein the workpiece is released by means of a solvent.

4. (Currently amended) The method as claimed in claim 3, wherein ~~a~~ the work carrier comprises a porous material which is permeable to said solvent ~~is used~~.

5. (Currently amended) The method as claimed in claim 1, wherein the porous material ~~is~~ comprises a ceramic, a glass, a glass ceramic, a metal, a sintered metal, a metal ceramic or a sintered material.

6. (Currently amended) The method as claimed in claim 1, ~~wherein the workpiece is thinned~~ further comprising thinning the workpiece on the work carrier.

7. (Previously presented) The method as claimed in claim 1, wherein the solid comprises a material selected from a group consisting of: wax, adhesive, a plastic material, or a double-sided adhesive tape.

8. (Previously presented) The method as claimed in claim 1, wherein the workpiece contains a semiconductor material.

9. (Previously presented) The method as claimed in claim 1, wherein the solid fills at least a portion of an intermediate space between the workpiece and the work carrier.

10. (Currently amended) A work carrier for processing a workpiece, said work carrier comprising a porous material including a plurality of pores at least a portion of which are interconnected, wherein the plurality of pores are configured to accommodate a portion of a liquefied solid upon application of vacuum pressure to the work carrier.

11. (Previously presented) The work carrier as claimed in claim 10, wherein the diameter of the work carrier is equal to the diameter of the semiconductor wafer.

12. (Currently amended) The method as claimed in claim 1 wherein fastening the workpeice comprises generating a vacuum ~~is generated~~ at the work carrier ~~for the fastening~~.

13. (Previously presented) The method as claimed in claim 12 wherein the vacuum is generated after the application of the solid in liquefied form and before the hardening of the solid.

14. (Previously presented) The method of claim 4 wherein, to separate the workpiece and work carrier, said solvent penetrates into passages from a pore or from the plurality of pores through the work carrier up to the solid.

15. (Currenltly amended) The method of claim 14 wherein the ~~reparations~~ separation of the workpiece from the work carrier preferably comprises ~~reparation~~ separation by the generation of a positive pressure on a side of the work carrier which is remote from the workpiece.

16. (Previously presented) The method as claimed in claim 1, wherein the average pore size has a value of between 20μm and 500μm, and wherein the porosity of the porous material has a value of between 20% and 50%.

17. (Previously presented) The method as claimed in claim 1, wherein the value of the open porosity of the porous material lies between 10% and 60%.

18. (Previously presented) The method as claimed in claim 1, wherein a portion of the plurality of pores include pore passages, wherein the pore passages comprise at least 10% of the pore volume, and wherein the pore passage traverse the porous material from a top side to a rear side of the carrier.

19. (Previously presented) The method as claimed in claim 1, wherein the porous material comprises a ceramic material manufactured according to one of German Institute Standard DIN 51056, 1985 or European Standard 623-2, 1992, and wherein the pores are arranged irregularly.

20. (Previously presented) The method as claimed in claim 1, wherein the average pore size ranges from 50μm to 100μm.

21. (Previously presented) The method as claimed in claim 1, wherein the value of the open porosity of the porous material lies between 20% and 50%.

22. (Previously presented) The work carrier as claimed in claim 10, wherein the plurality of pores comprise a branched pore network within the work carrier.

23. (Previously presented) The work carrier as claimed in claim 10, wherein a portion of the plurality of pores include pore passages, wherein the pore passages

comprise at least 10% of the pore volume, and wherein the pore passages traverse the work carrier from a top side to a rear side of the work carrier.